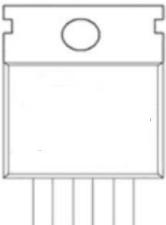
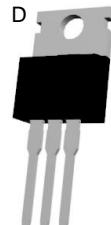
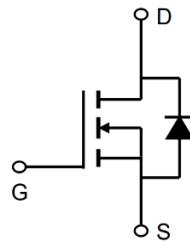


TMG190N06P
N-Channel Enhancement Mosfet

| General Description <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant Applications <ul style="list-style-type: none"> • Load switch • PWM | General Features <p> $V_{DS} = 60V$ $I_D = 190A$ $R_{DS(ON)} = 2.6m\Omega$ (typ.) @ $V_{GS}=10V$ </p> <p> 100% UIS Tested 100% R_g Tested </p>  | | |
|--|--|------------|------|
| P:TO-220AB | | | |
|  |   | | |
| Marking: G190N06 | | | |
| Absolute Maximum Ratings: ($T_c=25^\circ C$ unless otherwise noted) | | | |
| Parameter | Symbol | Limit | Unit |
| Drain-Source Voltage | V_{DS} | 60 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | 190 | A |
| Drain Current-Pulsed ^(Note 1) | I_{DM} | 680 | A |
| Maximum Power Dissipation($T_c=25^\circ C$) | P_D | 210 | W |
| Single pulse avalanche energy ^(Note 2) | E_{AS} | 1000 | mJ |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 175 | °C |
| Thermal Characteristics: | | | |
| Thermal Resistance,Junction-to-Case | $R_{\theta JC}$ | 0.7 | °C/W |

TMG190N06P
N-Channel Enhancement Mosfet

Electrical Characteristics: ($T_C=25^\circ C$ unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--|--------------|--|-----|------|-----------|------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 60 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=60V, V_{GS}=0V$ | - | - | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ± 100 | nA |
| On Characteristics | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2 | 3 | 4 | V |
| Drain-Source On-State Resistance ^(Note 3) | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=50A$ | - | 2.6 | 3.1 | m Ω |
| Forward Transconductance | g_{FS} | $V_{DS}=50V, I_D=75A$ | - | 180 | - | S |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS}=25V, V_{GS}=0V, f=1.0MHz$ | - | 7280 | - | pF |
| Output Capacitance | C_{oss} | | - | 760 | - | pF |
| Reverse Transfer Capacitance | C_{rss} | | - | 680 | - | pF |
| Switching Characteristics ^(Note 4) | | | | | | |
| Turn-on Delay Time | $td(on)$ | $V_{DD}=30V, I_D=40A, V_{GS}=10V, R_{GEN}=3\Omega$ | - | 27 | - | nS |
| Turn-on Rise Time | tr | | - | 25 | - | nS |
| Turn-Off Delay Time | $td(off)$ | | - | 90 | - | nS |
| Turn-Off Fall Time | tf | | - | 40 | - | nS |
| Total Gate Charge | Q_g | $V_{DS}=60V, I_D=40A, V_{GS}=10V$ | - | 186 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 46 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 70 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage | V_{SD} | $V_{GS}=0V, I_S=190A$ | - | - | 1.2 | V |

Notes:

1.Repetitive Rating: Pulse width limited by maximum junction temperature.

2.EAS condition : $T_j=25^\circ C, V_{DD}=50V, V_G=10V, L=0.5mH, R_g=25\Omega$

3.Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.

4.Guaranteed by design, not subject to production.

Characteristics Curves

Figure 1 Output Characteristics

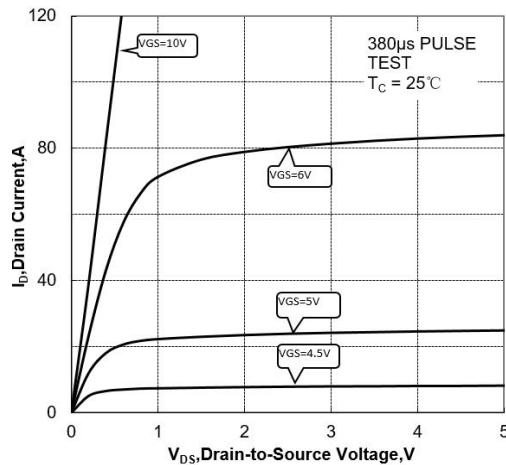


Figure 2 Transfer Characteristics

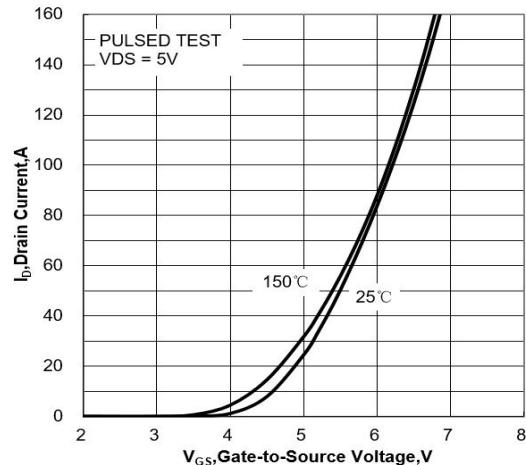


Figure 3 On-Resistance vs. ID and VGS

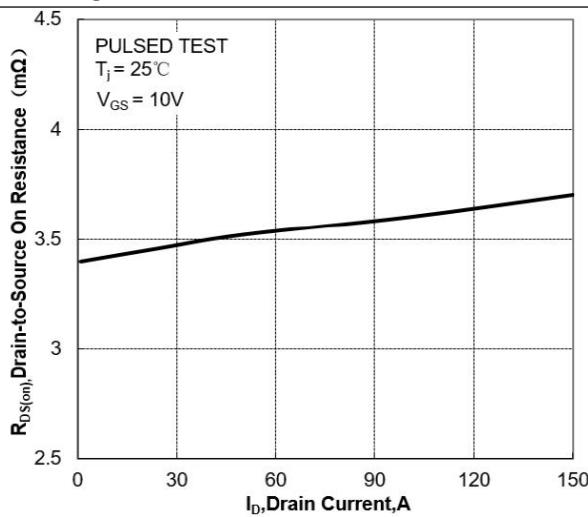


Figure 4 On-Resistance vs. Junction Temperature

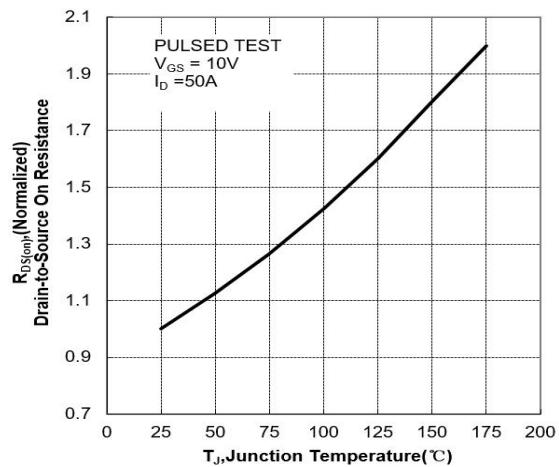


Figure 5 On-Resistance vs. VGS

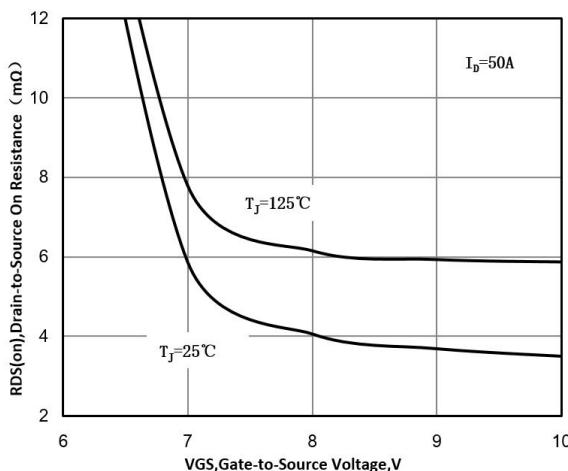
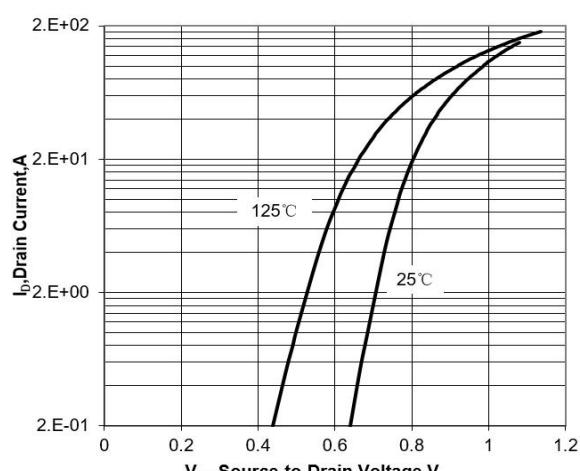


Figure 6 Body Diode Forward Voltage



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Figure 7 Gate-Charge Characteristics

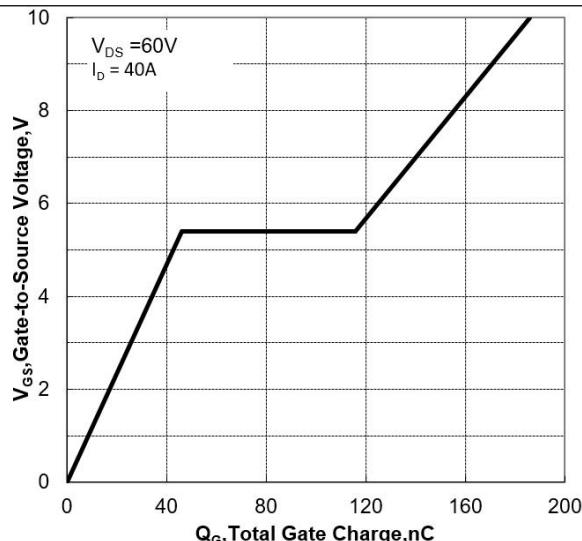


Figure 8 Capacitance Characteristics

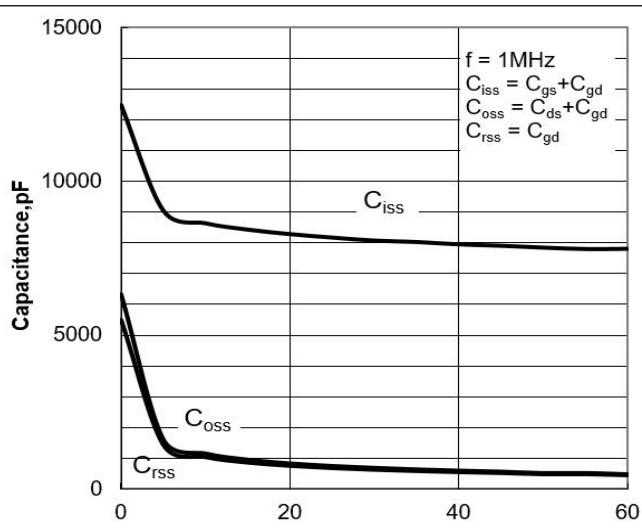


Figure 9 Maximum Forward Biased Safe Operation Area

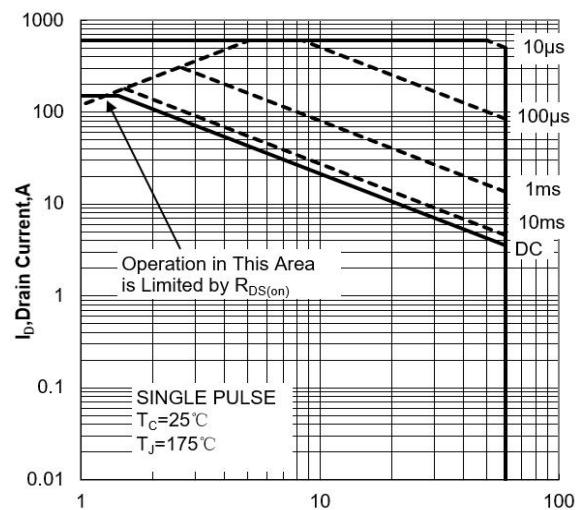


Figure 10 Single Pulse Power Rating Junction-to-Ambient

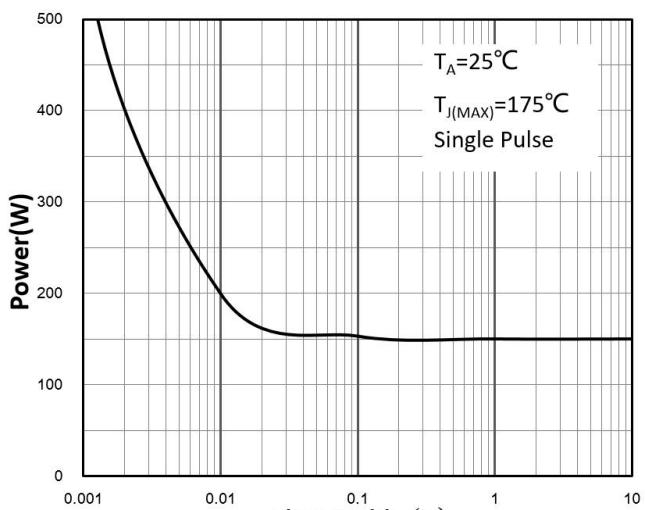
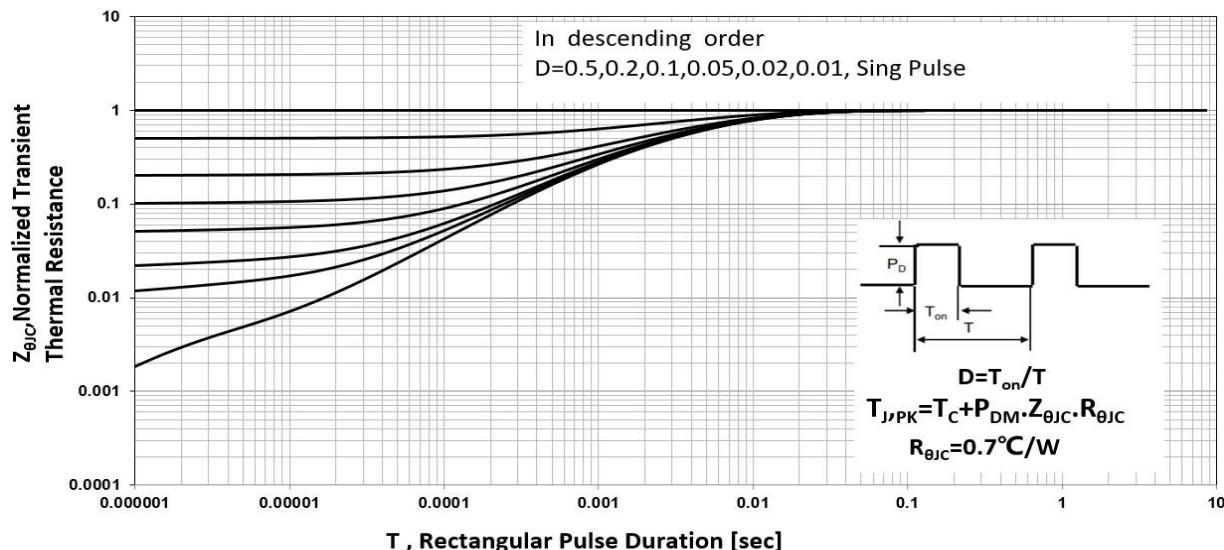


Figure 11 Normalized Maximum Transient Thermal Impedance



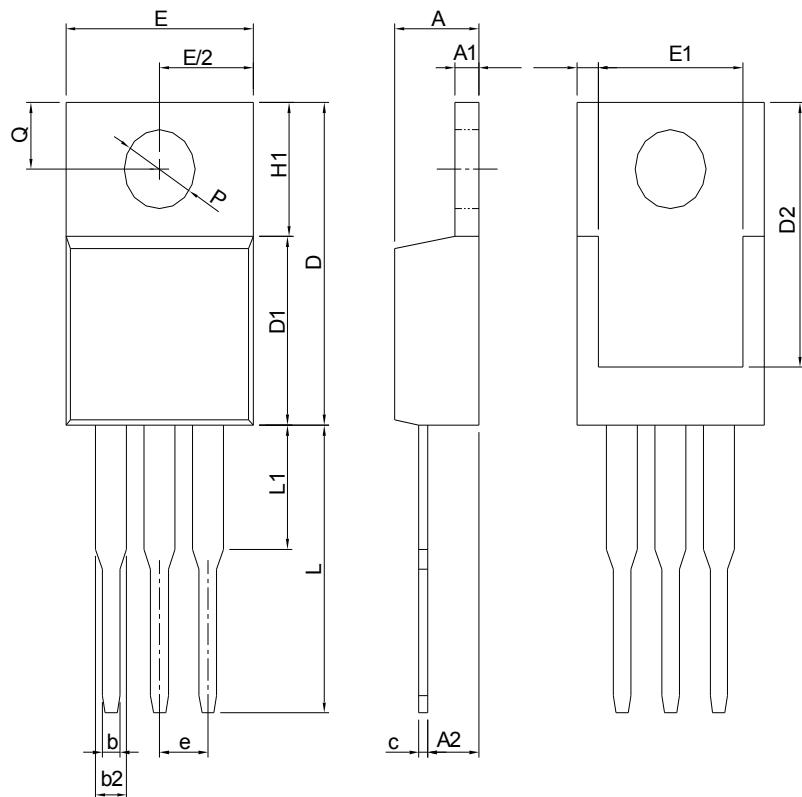
TMG190N06P

N-Channel Enhancement Mosfet

Test Circuit and Waveform

| Gate Charge Test Circuit | Gate Charge Test Waveform |
|--|--|
| | |
| Resistive Switching Test Circuit | Resistive Switching Test Waveforms |
| | |
| Unclamped Inductive Switching (UIS) Test Circuit | Unclamped Inductive Switching (UIS) Test Waveforms |
| | |
| Diode Recovery Test Circuit | Diode Recovery Test Waveforms |
| | |

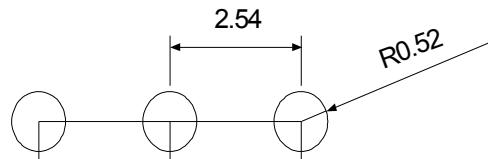
Package Information: TO-220AB



| SYMBOL | TO-220 | | | |
|--------|-------------|-------|-----------|-------|
| | MILLIMETERS | | INCHES | |
| | MIN. | MAX. | MIN. | MAX. |
| A | 3.56 | 4.83 | 0.140 | 0.190 |
| A1 | 0.51 | 1.40 | 0.020 | 0.055 |
| A2 | 2.03 | 2.92 | 0.080 | 0.115 |
| b | 0.38 | 1.02 | 0.015 | 0.040 |
| b2 | 1.14 | 1.78 | 0.045 | 0.070 |
| c | 0.36 | 0.61 | 0.014 | 0.024 |
| D | 14.22 | 16.51 | 0.560 | 0.650 |
| D1 | 8.38 | 9.02 | 0.330 | 0.355 |
| D2 | 12.19 | 13.65 | 0.480 | 0.537 |
| E | 9.65 | 10.67 | 0.380 | 0.420 |
| E1 | 6.86 | 8.89 | 0.270 | 0.350 |
| e | 2.54 BSC | | 0.100 BSC | |
| H1 | 5.84 | 6.86 | 0.230 | 0.270 |
| L | 12.70 | 14.73 | 0.500 | 0.580 |
| L1 | - | 6.35 | - | 0.250 |
| P | 3.53 | 4.09 | 0.139 | 0.161 |
| Q | 2.54 | 3.43 | 0.100 | 0.135 |

Note: Follow JEDEC TO-220 AB.

RECOMMENDED LAND PATTERN



UNIT: mm